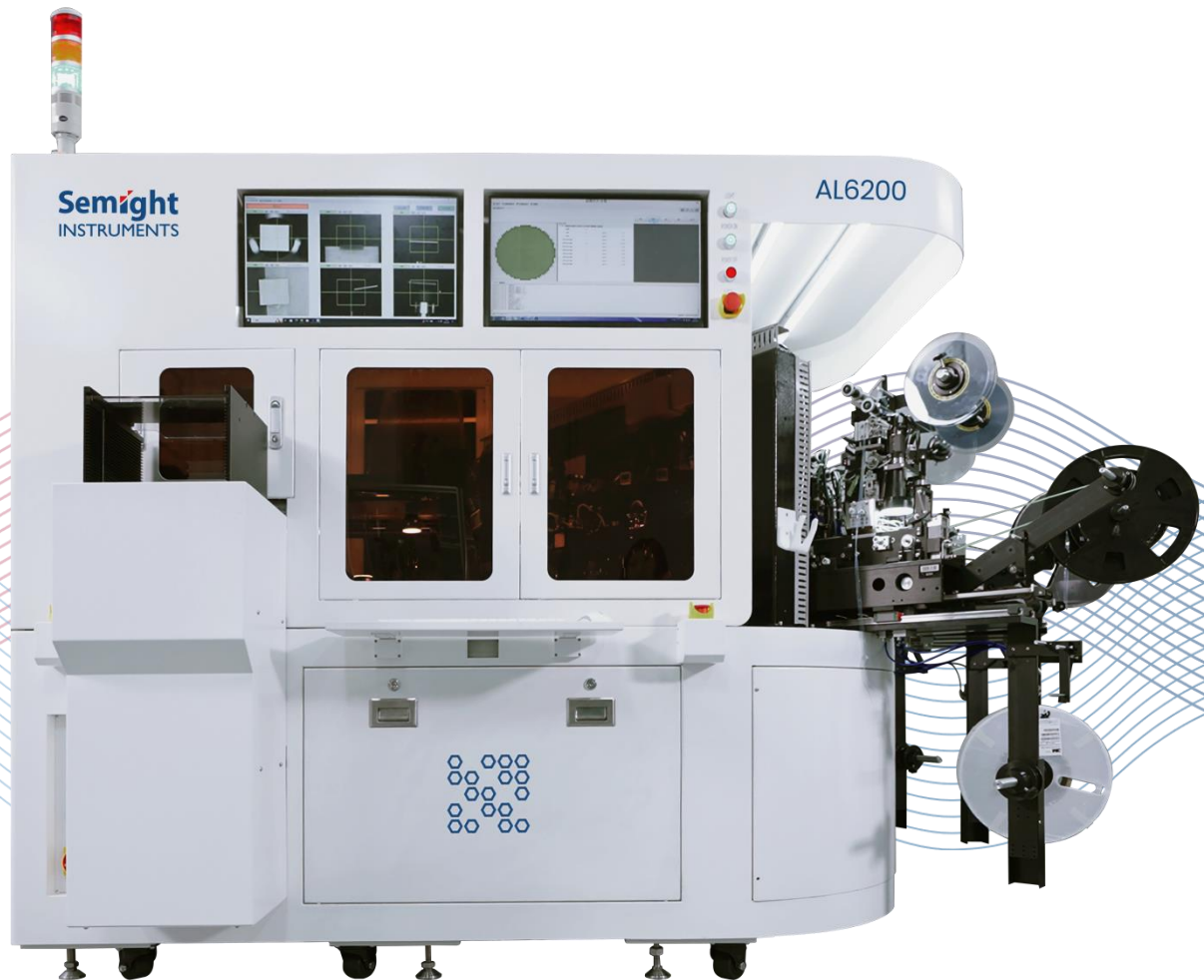


# AL6200

Die Inspection Sorting System

Version 1.0



## 1. Product Description

Semright AL6200 Die Sorting system is mainly used in power chip die level visual inspection and sorting. The sorting condition is according to the different test specification and visual inspection. AL6200 supports up to 8pcs different classifications and finish the six sides visual inspection before the sorting. The system supports frame ring input and tape reel output(tray is optional);

## 2. Key Features

- 1) Support expansion UV/blue tape frame automatic, so the non-expansion frame can be produced normally
- 2) Support QR code/bar code scanning, recording wafer information, including Lot ID, wafer ID, tape ID. For abnormal QR/bar code scanning, system can be manual input. For the tape reel without QR code, it can be numbered and recorded automatically
- 3) Support visual access to mapping information, software achieve data MAP function
- 4) The feeding system can rotate wafer at a maximum of 360° according to the required Angle
- 5) Support tape width from 8mm to 24mm, the general tape width is 12mm
- 6) Supports 8pcs tape reel output, and tray is optional
- 7) UPH $\geq$  2K(according to the production process and inspection condition)
- 8) Support chip six-side inspection, and the maximum defect accuracy 10 $\mu$ m
- 9) Supports single chip traceability and data upload, and supports MES docking
- 10) The software supports three-level rights management and multi-account management

## 3. System Function

Parameter	Index
Applicable product	SiC, IGBT chip

Wafer size	6' ' & 8' '
AOI function	Six sides
Input mode	Frame ring
Output mode	Tape reel, Tray
Sealing mode	Heat seal
Nitrogen protection	>0.6 MPa
Equipment power	4.5 kW
Dimension (mm)	2885 × 2100 × 1850
SECS/GEM protocol	Support

#### 4. General Indicators and Software

Parameter	Index
Operating temperature	15-30 °C
Storage temperature	-10-50 °C
Working humidity	40-70%
Storage humidity	<90%
Working altitude	0-2 km
Power supply	200-240 VAC, 30 A, 50 Hz
Air supply pressure	>0.6 Mpa
Software system	VisualStudio2019
Software language environment	C# (.Net Frame Work 4.7.2)
Software function	Test plan editing, test condition and parameter Spec setting, chip

	<p>description,</p> <p>MES interface, test data management and analysis, calibration</p> <p>maintenance, fault diagnosis</p>
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## 5. Technical Specifications

Parameter	Index
Wafer loading method	Iron ring & child ring
Chip Specification (mm)	maximum size 8*8*0.3, minimum size 2.5*2.5*0.18
Braid specification (mm)	compatible with 7 "to 13" reel sizes, tape width 8mm to 24mm
Surface detection	foreign matter, crack, scratch, defect 10µm on chip surface
Side detection	chip side size, crack, collapse, foreign body min defect 20µm
Blanking parameter	8-channel tape reel with expendable 4 "tray(optional)
Tension after hot sealing	≥20 g

## 6. Ordering information

AL6200	Die inspection sorting system
Select parts information	
Suction nozzle	Custom suction nozzle according to customer chip size
Attachment	
System operation manual, system software manual, system maintenance manual, factory verification report, list of wearing parts	

## Contact us

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\*This information is subject to change without notice.